

Ongoing activities at CiS

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At this time, the CiS research institute is engaged in developments of radiation detector technologies on several different fields. Current projects are dealing e.g. with defect engineering, active edge sensors, large area thinned sensors and sensor-chip packaging technologies.

For large area sensors, the need for smaller thicknesses can be approached by etching cavities to the sensors back side while guaranteeing stability on wafer level by thick frames at the edges. First tests with Membranes up to 4x4cm² in size will be shown.

Several approaches to realize active edges for radiation detectors are under development. As a first step, we started TCAD-simulations to optimize the layout and technology parameters.

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